

Bill of Materials

TI DESIGNS

TIDA-00384 Main Board (2513854)

Item	Qty	Reference	Value	Part Description	Manufacturer	Manufacturer Part Number	Alternate Part	PCB Footprint	Note
1	5	C1,C2,C40,C41,C63	100uF	CAP CER 100UF 16V 20% X5R 1210	Taiyo Yuden	EMK325ABJ107MM-T		1210	
2	59	C3,C7,C8,C9,C10,C12,C14,C16,C17,C18,C20,C22,C23,C24,C25,C26,C27,C28,C29,C30,C33,C34,C35,C37,C43,C44,C47,C48,C54,C55,C57,C64,C65,C66,C67,C68,C69,C72,C73,C74,C75,C76,C77,C78,C79,C80,C81,C82,C83,C84,C85,C86,C87,C88,C89,C90,C91,C92,C93	0.1uF	CAP CER .1UF 16V X7R 0402	TDK	C1005X7R1C104K050BC		0402_AVXA	
3	3	C4,C52,C53	4.7uF	CAP CER 4.7UF 6.3V 20% X5R 0402	TDK	C1005X5R0J475M		402	
4	9	C5,C6,C13,C15,C19,C50,C51,C59,C62	10uF	CAP CERAMIC 10UF 6.3V X5R 0603	TDK	C1608X5R0J106M080AB		603	
5	4	C11,C21,C31,C32	1000pF	CAP CERAMIC .001UF 16V X7R 0402	Yageo	CC0402KRX7R78B102		402	
6	3	C36,C39,C58	2.2uF	CAP CER 2.2UF 6.3V X5R 0402	TDK	C1005X5R0J225M		402	
7	4	C38,C42,C49,C70	1uF	CAP CER 1.0UF 10V X5R 0402	TDK	C1005X5R1A105M		402	
8	1	C45	2200pF	CAP CER 2200PF 25V X7R 0402	Murata	GRM155R71E222KA01D		402	
9	1	C56	0.22uF	CAP CER 0.22UF 25V 10% X5R 0402	TDK	C1005X5R1E224K050BC		402	
10	2	C61,C71	18pF	CAP CER 18PF 50V COG 5% 0402	TDK	C1005COG1H180J		402	
11	1	D1	BAS70-05	DIODE SCHOTTKY 70V 70MA SOT23	Diodes Incorporated	BAS70-05-F		SOT-23	
12	2	D2,D3	RCLAMP0502B.TCT	TVS DIODE 5VWM 15VC 10SLP	Semtech	RCLAMP0502B.TCT		Semtech_SLP2510P8_10_pin	
13	1	D4	PMEG4002EL	SCHOTTKY RECT 40V 0.2A SOD882	NXP Semiconductors	PMEG4002EL,315		SOD882	
14	6	D5,D6,D7,D9,D15,D16	green	LED 565NM WTR CLR GREEN 1206 SMD	Lumex	SML-LX1206GC-TR		1206	
15	4	D8,D10,D12,D14	blue	LED INGAN/SIC U-BLUE CLR 1206SMD	Lumex	SML-LX1206USBC-TR		1206	
16	6	F1,F2,F3,F4,F5,F6	MMZ1608S601A	FERRITE CHIP 600 OHM 500MA 0603	TDK	MMZ1608S601A		603	
17	1	J1	HDR,14P,2R	CONN HEADER 14POS .100in DL GOLD	Samtec	TSW-107-14-G-D		HDR14P_2R_100mil	
18	1	J2	SJ-43516-SMT-TR	CONN AUDIO JACK 3.5MM 4COND SMD	CUI Stack	SJ-43516-SMT-TR		CUI_SJ-43516-SMT	
19	1	J3	HDR,3P,1R	PLUG	Samtec	TSW-103-07-G-S		TSW-103-07-G-S	
20	1	J4	HDMI	CONN RCPT 19POS HDMI RT ANG SMD	Molex	47151-0001		Molex_47151-0001	
21	1	J5	HDR,4P,1R	PLUG	Samtec	TSW-104-14-G-S		HDR4P_1R	
22	1	J6	QTH-030-02-L-D-A	CONN HEADER HS .5MM 60POS DL AU (stacking ht	Samsung	QTH-030-02-L-D-A		Samtec_QTH-030-xx-x-D-A	
23	1	J7	USB,Type-B	CONN RECEPT USB TYPE B PCB	mill-max	897-43-004-90-000000		USB_B	
24	2	J10,J11	HDR,2P,1R	CONN HEADER 2POS .100 VERT GOLD	Molex	22112022		22Series_2P	
25	1	J12	Pwr Jack, 2.5mm pin	CONN POWERJACK MINI RA HYBRID	Switchcraft	RAPC712X		SWITCHCRAFT_RAPC712X	
26	3	L1,L2,L3	2.2uH	INDUCTOR 2.2UH 20% 1300MA 1008	Murata	LQM2HPN2R2MGOL		1008_2p5mmx2mm	
27	5	PB_UP1,PB_SEL1,PB_RIGHT1,PB_LEFT1,PB_DOWN1	KT11B15M	SWITCH TACT 0.64MM SILV GWING	C&K	KT11B15M34LFS		KT11B15M	
28	1	Q1	DMN26D0UT	MOSFET N-CH 20V 230MA SOT523	Diodes Incorporated	DMN26D0UT		SOT_523	
29	3	RA1,RA2,RA3	22	RES ARRAY 22 OHM 8 RES 1506	Panasonic	EXB-2HV220V		EXB-2HV	
30	3	R2,R3,R36	180k	RES 180K OHM 1/16W 1% 0402 SMD	Yageo	RC0402FR-07180KL		402	
31	1	R4	3k	RES 3K OHM 1/10W 1% 0402 SMD	Panasonic	ERJ-2RKF3001X		402	
32	1	R5	1.5k	RES 1.50K OHM 1/10W 1% 0402 SMD	Panasonic	ERJ-2RKF1501X		402	
33	10	R6,R12,R64,R65,R66,R73,R74,R75,R76,R77	22	RES 22.0 OHM 1/16W 1% 0402 SMD	Yageo	RC0402FR-0722RL		402	
34	2	R7,R51	4.7k	RES 4.7K OHM 1/10W 1% 0402 SMD	Panasonic	ERJ-2RKF4701X		402	
35	2	R8,R14	47k	RES 47.0K OHM 1/10W 1% 0402 SMD	Panasonic	ERJ-2RKF4702X		402	
36	19	R9,R10,R13,R22,R25,R29,R31,R34,R40,R44,R49,R50,R55,R80,R81,R84,R85,R89,R90	0	RES 0.0 OHM 1/16W 0402 SMD	Panasonic	ERJ-2GE0R00X		402	
37	18	R11,R18,R23,R37,R38,R42,R43,R46,R52,R53,R54,R58,R72,R86	10k		Panasonic	ERJ-2RKF1002X		402	
38	9	R15,R16,R17,R19,R20,R21,R26,R27,R28	30.1	RES 30.1 OHM 1/16W 1% 0402 SMD	Panasonic	ERJ-2RKF30R1X		402	
39	2	R24,R30	100k	RES 100K OHM 1/10W 1% 0402 SMD	Panasonic	ERJ-2RKF1003X		402	

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40	1	R32	442k	RES 442K OHM 1/10W 1% 0402 SMD	Panasonic	ERJ-2RKF4423X		402	
41	1	R33	887k	RES 887K OHM 1/16W 1% 0402 SMD	Panasonic	ERJ-2RKF8873X		402	
42	2	R35,R47	360k	RES 360K OHM 1/16W 1% 0402 SMD	Yageo	RCD402FR-07360KL		402	
43	3	R39,R41,R45	1k	RES 1.00K OHM 1/10W 1% 0402 SMD	Panasonic	ERJ-2RKF1001X		402	
44	1	R48	78.7k	RES 78.7K OHM 1/10W 1% 0402 SMD	Panasonic	ERJ-2RKF7872X		402	
45	3	R57,R60,R61	33.2	RES 33.2 OHM 1/16W 1% 0402 SMD	Panasonic	ERJ-2RKF33R2X		402	
46	1	R59	300k	RES 300K OHM 1/16W 1% 0402 SMD	Yageo	RCD402FR-07300KL		402	
47	5	R67,R68,R71,R78,R97	100	RES 100 OHM 1/10W 1% 0402 SMD	Panasonic	ERJ-2RKF1000X		402	
48	1	R69	2M	RES 2M OHM 1/10W 5% 0402 SMD	Panasonic	ERJ-2GEJ205X		402	
49	1	R70	1M	RES 1M OHM 1/10W 1% 0402 SMD	Panasonic	ERJ-2RKF1004X		402	
50	1	R82	200	RES 200 OHM 1/8W 5% 0805 SMD	Panasonic	ERJ-6GEYJ201V		805	
51	5	R87,R92,R94,R96,R99	470k	RES 470K OHM 1/10W 1% 0402 SMD	Panasonic	ERJ-2RKF4703X		402	
52	1	R88	270	RES 270 OHM 1/10W 1% 0402 SMD	Panasonic	ERJ-2RKF2700X		402	
53	1	SW1	GT11MSCBE	SWITCH TOGGLE SPDT ULTRAMINI SMD	C&K	GT11MSCBE		GT11MSCBE	
54	9	TPGND1,TPGND2,TPGND3,TPGND4,TPGND5,TPGND6,TPGND7,TPGND8,TPGND9	TP_BLK	TEST POINT PC MINI .040inD BLACK	Keystone	5001		KEYSTONE_TP_MINIATURE	
55	3	U1,U12,U17	TPS62260DDCT	IC REG BUCK SYNC ADJ TSOT23-5	Texas Instruments	TPS62260DDCT		TSOT-23_DDC_R-PDSO-G5	
56	1	U2	TLV320DAC3101	IC STEREO AUD DAC CLASS-D LP 32QFN	Texas Instruments	TLV320DAC3101RHBR		QFN-32_RHB_S-PVQFN-N32	
57	2	U3,U4	NC7S266P5X	IC BUS SWITCH SPST SGL LV SC70-5	Fairchild	NC7S266P5X		SC70-5	
58	4	U5,U6,U7,U8	SN74AVC4T245RSV	IC BUS TRANSCVR 4BIT 16-UQFN	Texas Instruments	SN74AVC4T245RSVR		UQFN16_RSV_R-PQFP-N16	
59	1	U9	TPS2061CDBVT	IC PWR DIST SWITCH SGL SOT23-5	Texas Instruments	TPS2061CDBVT		SOT_23_5_DBV_R-PDSO-G5	
60	1	U10	TPS71501DCK	IC LDO REG ADJ 50MA MCPWR SC70-5	Texas Instruments	TPS71501DCKR		SC70_5_DCK_R-PDSO-G5	
61	1	U11	CY7C65215-32LTXI	IC USB TO UART BRIDGE DUAL 32QFN	Cypress	CY7C65215-32LTXI		CY7C65215_32pin_QFN	
62	7	U13,U15,U16,U20,U25,U28,U29	SN74AUP1G07DCK	IC INVERTER SINGLE 1INPUT SC705, open drain	Texas Instruments	SN74AUP1G06DCKR		U_5_DCK	
63	1	U14	TXS0102	IC VOLT-LEVEL TRANSLATOR 8-US8	Texas Instruments	TXS0102DCU		VSSOP-8_DCU	
64	1	U18	TPD2E001DRY	IC ESD-PROT ARRAY 2CH 6-SON	Texas Instruments	TPD2E001DRYR		U_6_DRY	
65	1	U19	M24C02-WMN6TP	IC EEPROM 2KBIT 400KHZ 8SOIC	Stmicroelectronics	M24C02-WMN6TP		SOIC-8_3p90mm_wide	
66	4	U21,U26,U32,U33	SN74AUP1G07DCK	IC BUFF/DVR LOW PWR N-INV SC705, open drain	Texas Instruments	SN74AUP1G07DCKR		U_5_DCK	
67	2	U22,U23	TPD4S009DBVR	IC 4CH ESD SOLUTION SOT23-6	Texas Instruments	TPD4S009DBVR		SOT23-6_DBV_R-PDSO-G6	
68	1	U24	ITE6801	HDMI Rcvr	ITE Tech Inc	ITE6801FN		ITE6801_76pin_QFN	
69	1	U30	MSP430F2274IDAR	IC MCU 16BIT 32KB FLASH 38TSSOP	Texas Instruments	MSP430F2274IDAR		TSSOP_38_DA_R-PDSO-G	
70	1	X1	27.000MHz	CRYSTAL 27MHZ 18PF SMD	Abrakon	ABM8-27.000MHZ-B2-T		Abrakon_ABM8	

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